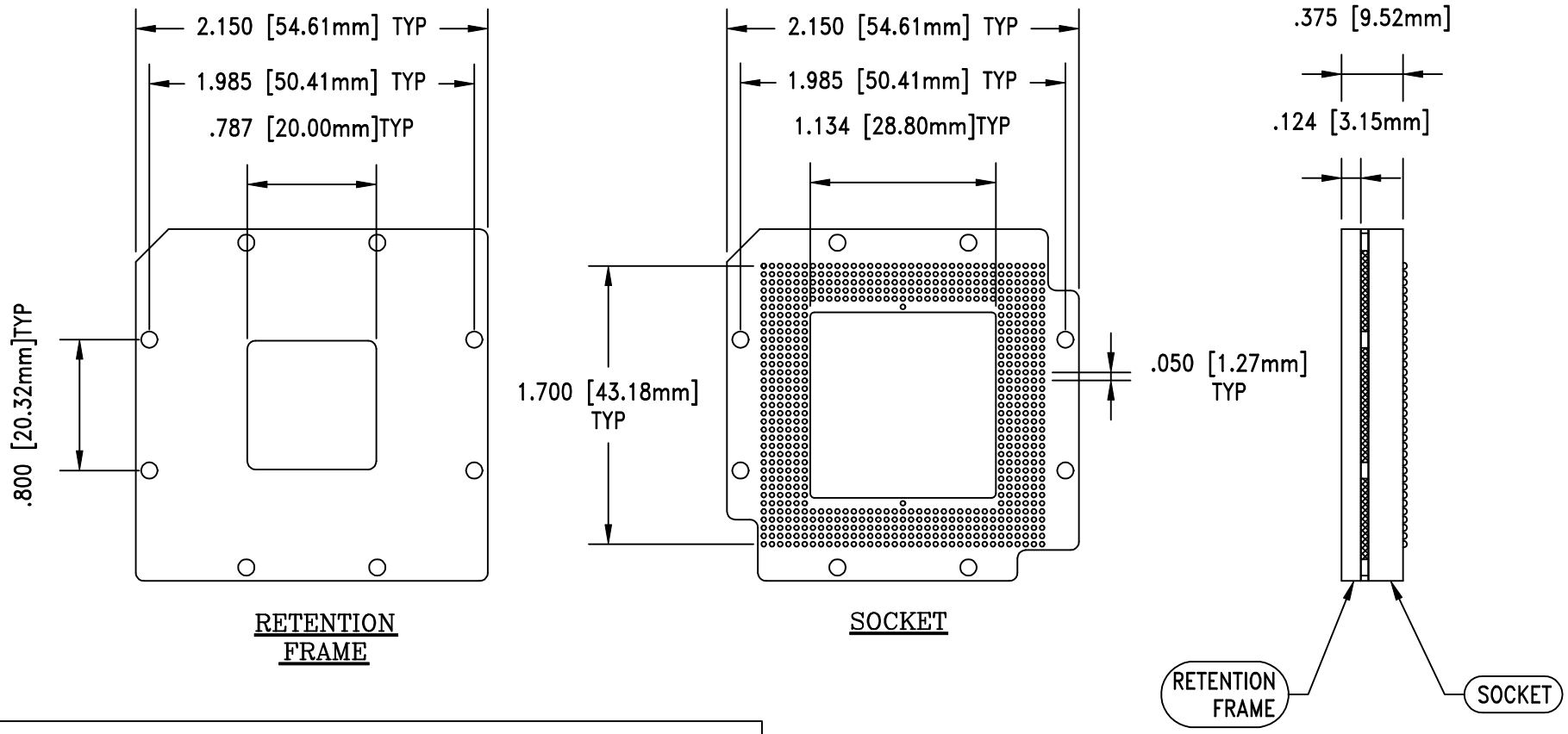
REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	4/28/00	M.D.
B	UPDATED SOCKET FROM VENDOR	3/30/01	A.F.

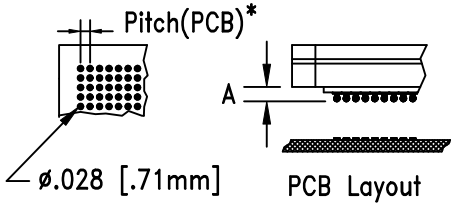
SKT950

DOD 4950

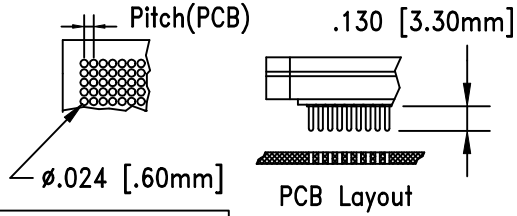


RECOMMENDED PAD LAYOUT

SMT STYLE
−29(RC) & −30(SM) TYPE



THRU HOLE STYLE
−70(ET) TYPE



XX(YY)= SOLDERTAIL STYLE

30= standard SMD ("A" = .047 [1.20mm])
29= raised SMD ("A" = .197 [5.00mm])

PIN DIAMETER FOR −70(ET)=.018 [.45mm]
BALL DIAMETER FOR −29(RC) & −30(SM)=.026 [.66mm]

* The pitch dimension depends on your Ball Grid Array

PACKAGE SPECIFICATIONS	
PIN COUNT	= 652
LEAD PITCH	= 1.27mm
GRID SIZE	= 35x35
PACKAGE SIZE	= UNKNOWN

ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED

Emulation Technology, Inc.
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SHEET:	DATE:	REVISION:	ASSEMBLY DRAWING
1 OF 1	4−28−00	B	
CHECKED: PAULA OLSON	DRAWN: MIGUEL DELGADILLO		ITEM: S−BGA−35−652−YY
DO NOT SCALE DRAWING			DESCRIPTION: BPW−652−2BG035−XX